

Preface

2013 2nd International Conference on Manufacturing Engineering and Process (ICMEP 2013) was held in Vancouver, Canada, April 13-14, 2013. The conference provides a platform to discuss Manufacturing Engineering and Process etc. with participants from all over the world, both from academia and from industry. Its success is reflected in the papers received, with participants coming from several countries, allowing a real multinational multicultural exchange of experiences and ideas.

The present volumes collect accepted papers and represent an interesting output of this conference. This book covers these topics: Materials Engineering and Technology, Mechanical Engineering, Design Technology and Engineering, Applied Thermodynamics, Heat Transfer, Energy Conversion, Electrical Engineering and Electric Machines, Power System and Energy Engineering, Its Applications, Instrumentation, Measurement Technologies, Analysis and Methodology, Electronics and Integrated Circuits, Embedded Technology and Applications, Mechatronics and Robotics, Modern Control, Automation and Reverse Engineering, Civil Engineering, Manufacturing and Industrial Engineering, Management Applications, Mathematics, Signal Processing and Data Mining, Information Technologies and Networks.

This conference can only succeed as a team effort, so the editors want to thank the international scientific committee and the reviewers for their excellent work in reviewing the papers as well as their invaluable input and advice.

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